

ABSTRACT OF THE DISCLOSURE

It is an object of the present invention is to provide a method for manufacturing a multi-layered ceramic electronic component which can 5 reliably prevent a multi-layered unit including a ceramic green sheet and an electrode layer from being damaged and efficiently laminate a desired number of the multi-layered units, thereby manufacturing the multi-layered ceramic electronic component.

The method for manufacturing a multi-layered ceramic electronic 10 component according to the present invention includes a step of laminating a plurality of multi-layered units each formed by laminating a ceramic green sheet, an electrode layer and a release layer on a support sheet in this order, the method further including steps of positioning the multi-layered unit on a base substrate so that the surface of the release 15 layer is contact with an agglutinant layer formed on the surface of the base substrate in such a manner that the bonding strength between itself and the support substrate is higher than the bonding strength between the support sheet and the ceramic green sheet and lower than the bonding strength between itself and the release layer, pressing it and 20 laminating multi-layered units on the base substrate.